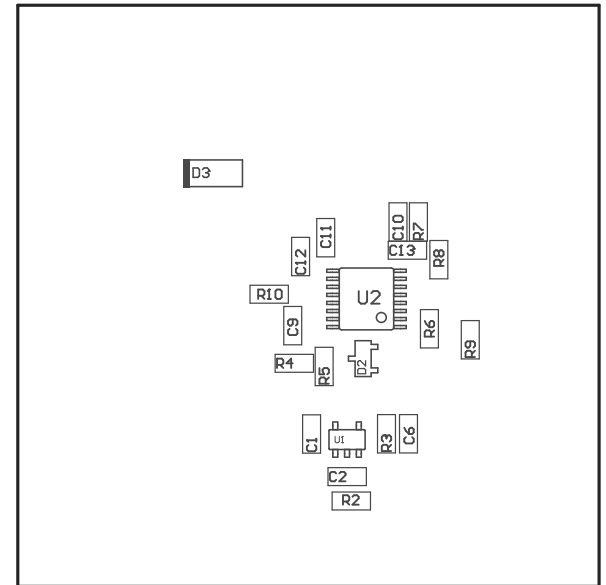


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30284	REV: B	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/1/2017	13:14:08	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30284	REV: B	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/1/2017	13:14:09	TEXAS INSTRUMENTS

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